

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739437000

Status:

Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Closed End, 144 Circuits

Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

[73943](#)

Application

Backplane

Comments

Solder Tail

Component Type

PCB Header

Overview

[hdm](#)

Product Name

HDM®

Style

N/A

Physical

Circuits (Loaded)

144

Circuits (maximum)

144

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Number of Columns

24

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length (in)

0.138 In

PC Tail Length (mm)

3.50 mm

PCB Retention

None

PCB Thickness Recommended (in)

0.098 In

PCB Thickness Recommended (mm)

2.50 mm

Packaging Type

Tube

Pitch - Mating Interface (in)

0.079 In

Pitch - Mating Interface (mm)

2.00 mm

Plating min: Mating (µin)

30

Plating min: Mating (µm)

0.75

Plating min: Termination (µin)

100

Plating min: Termination (µm)

2.5

Stackable

Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55°C to +105°C



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73943Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling FAQ	
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.	
Global	
Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73943-001

HDM and High Density Metric are trademarks of Amphenol Corporation

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NOTES:

1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK.
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



SEE NOTE 6

PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

MODIFY FINISH NOTE
EC NO: UCP2007-2259
IDRW:MSI/BARRA 2007/03/13
CHKD:BBARKER 2007/03/21
APPR:SMILLER 2007/03/22

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±---	±---
3 PLACES	±---	±---
2 PLACES	±0.05	±---
1 PLACE	±0.10	±---
ANGULAR	±1/2°	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
JB INGHAM	1998/01/13
CHECKED BY	DATE
SREED	1998/01/13
APPROVED BY	DATE
CBIXLER	1998/01/13
MATERIAL NO.	SEE CHART

SCALE
2:1

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

TITLE
SALES ASSY HDM BACKPLANE
END WALL OPTION
SOLDER TAIL VERSION

MOLEX MOLEX INCORPORATED

DOCUMENT NO.
SD-73943-001

SHEET NO.
1 OF 2

MATERIAL NUMBER ASSIGNMENT

73943-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1
EC NO. U81577
DRWN:JBINGHAM 98/02/03
CHK: REED 98/02/03
APPR:CBIXLER 98/02/03

DESCRIPTION
MAJOR
CRITICAL

GENERAL TOLERANCES:
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.	±.
3 PLACES	±0.	±.
2 PLACES	±0.N/A	±.
1 PLACE	±0.NA/	±.

ANGULAR: ± °

DRAFT WHERE APPLICABLE MUST
REMAIN WITHIN DIMENSIONS

SCALE
NO:NE

DESIGN UNITS
☒mm ☐INCH

DRAWN BY & DATE
JBINGHAM 98/01/13

CHECKED BY & DATE
SREED 98/01/13

APPROVED BY & DATE
CBIXLER 98/01/13

CAD FILENAME
S73943X2.DGN

TITLE: SALES ASS'Y, HDM BACKPLANE
END WALL OPTION
SOLDER TAIL VERSION

MOLEX INCORPORATED

MATERIAL NO. SEE CHART

DRAWING NO. SD-73943-001

SHEET NO. 2



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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